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DIAMOND GRINDING WHEELS (resin bond)





Diamond grinding wheels

Resin bonded synthetic diamond grinding surface

About the synthetic diamond

The synthetic diamond originates through the action of high pressure and temperature on the natural graphite. Through various levels of pressure and temperature different degrees of hardness of the synthetic diamond grain are achieved. The requested grit size is then achieved through crushing, grinding, sifting and rinsing.

Diamond is the hardest known material and in the hardness scale it is assigned number 10. Besides its hardness, this material is also exceptional for its good thermal conductivity and resistance to temperatures up to 700C (1292F) and for its resistance to all kinds of chemical effect at standard temperatures.

Table of grain size of the synthetic diamond powder								
FEPA ISO 6106	Dimension µm	US Standard ASTM E 11	ČSN 224015					
D 151	150/125	100/120	160/125					
D 126	125/106	120/140	125/100					
D 107	106/90	140/170	100/80					
D 91	90/75	170/200	100/00					
D 76	75/63	200/230	80/63					
D 64	63/53	230/270	63/50					
D 54	53/45	270/325	50/40					
D 46	45/38	325/400	50/40					

Contact for the receipt of orders

Address: VID GlassPartner s.r.o., U nádraží 1297, 511 01 Turnov, Czech Republic E-mail: info@vid-glasspartner.com

Charge-free advisory service

Besides suggesting the proper wheel shape and its specific grinding qualities (free of charge), we offer an advisory service as well as a thorough counseling in areas of individual technologic steps and complex technologies according to the needs and demands of our customers. Designing of such technologic steps will be charged after mutual consent and consultation with the sales department.

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The charge-free advisory service email account: info@vid-glasspartner.com



Diamond grinding wheels

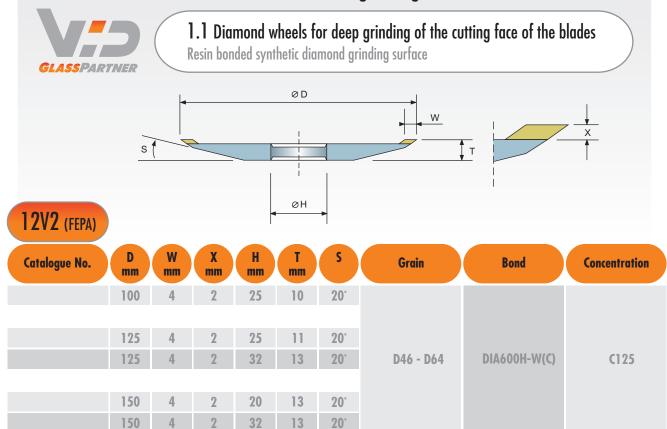
Resin bonded synthetic diamond grinding surface

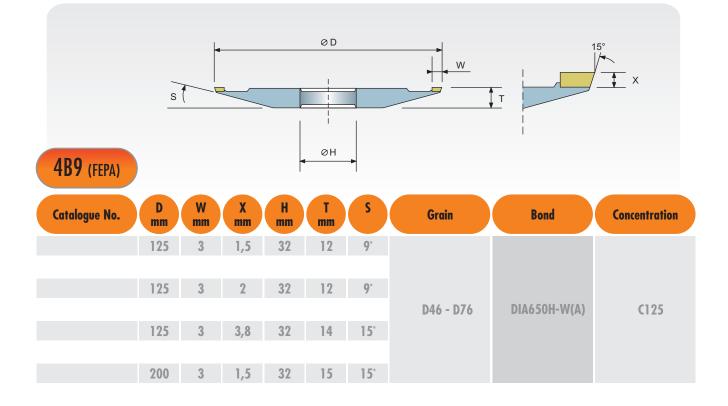
The resin bonded synthetic diamond wheels for grinding and sharpening of tungsten carbide woodworking tools:

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In case the tool you are looking for is not included in the catalogue, please contact us at: info@vid-glasspartner.com.









1.1 Diamond wheels for deep grinding of the cutting face of the blades Resin bonded synthetic diamond grinding surface



For deep <u>wet</u> grinding of the cutting face it is recommended to use two types of bonding: DIA650H-W(A) and DIA600H-W(C).

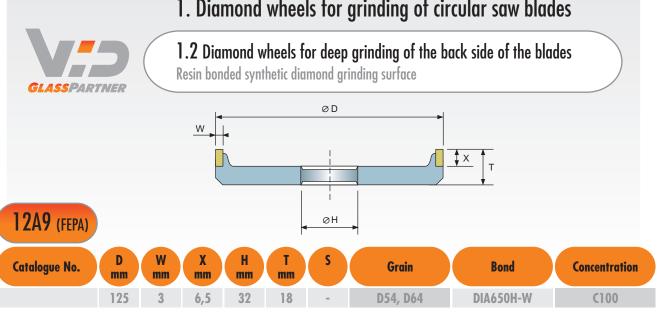
For grinding of the cutting face of the blades with intensive regimes of grinding, it is recommended to use the bond type DIA650H-W(A), for example in case of <u>wet</u> grinding using emulsion as the coolant at manufacture of the blade with the grinding depth of t=0.15mm or in case of <u>wet</u> re-sharpening of the blade with the grinding depth of t=0.15mm.

In some cases the intensive regimes of grinding are not necessary. In such cases we recommend to use the bond type DIA600H-W(C), for example for <u>wet</u> re-sharpening of the blade with the grinding depth of t=0.02-0,05 mm.

The wheels of the type 4B9 are mostly used for more intensive regimes of grinding (for ex. in production) than the wheels of the type 12V2. These are mostly used for re-sharpening.









For wet grinding of the back side of the blade it is recommended to use the bond type DIA650H-W(A), using emulsion as the coolant.

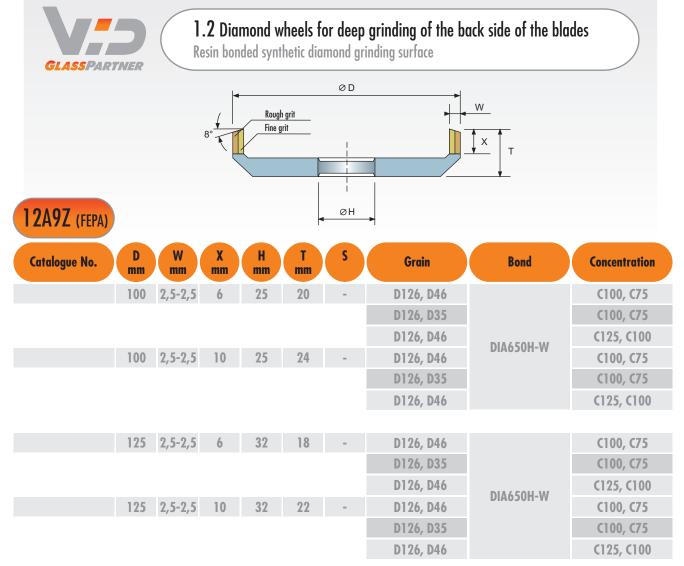
For deep wet grinding of the ridge of the blade with intensive regimes of grinding, it is recommended to use the bond type DIA650H-W(A), using emulsion as the coolant, for example at production of the blade with the grinding depth of t=0.4mm and feed speed s=6mm/s or in case of wet re-sharpening of the blade with the grinding depth of t=0.2mm and feed speed s=12mm/s.

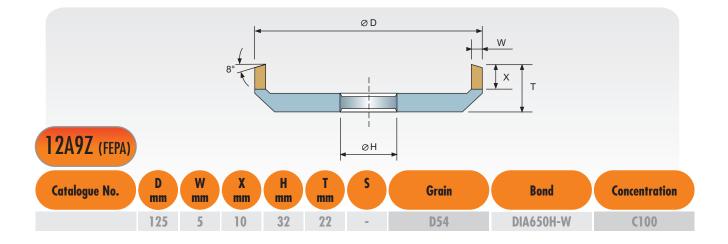
The use of a finer grain D35 (30-40 um) instead of the traditionally used D46 on the inner side reduces the roughness of the processed surface by 10-15% while keeping the same lifetime of the wheel.

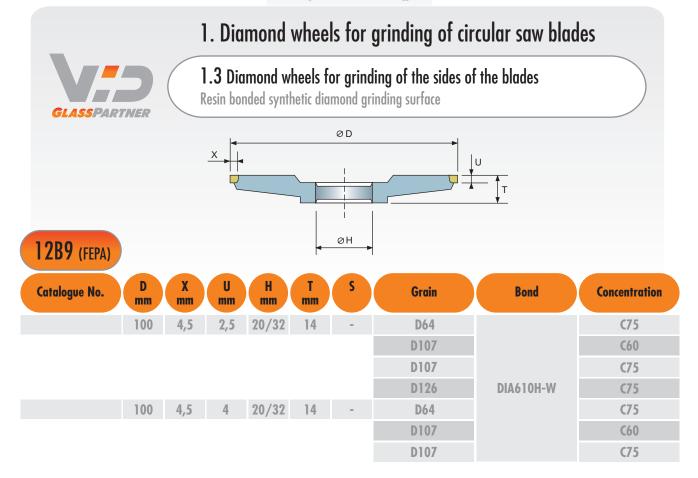
The use of the wheels with higher concentration C125/C100, which are more expensive but have a longer lifetime, can be in some cases economically more efficient.

The wheels of the type 12A9 with only one size of grain in their diamond layer are recommended for smooth grinding of the back side of the blade (e.g. with the grinding depth of t=0.01mm). The wheels of the type 12A9Z with two sizes of grain in their diamond layer are, on the contrary, better for use wherever deep grinding is intended.

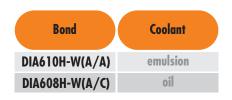








For deep wet grinding of the ridge of the blade it is recommended to use the bond type DIA610H-W(A/A) using emulsion as the coolant or bond type DIA608H-W(A/C) using oil as the coolant.





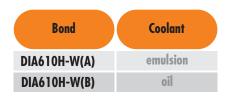


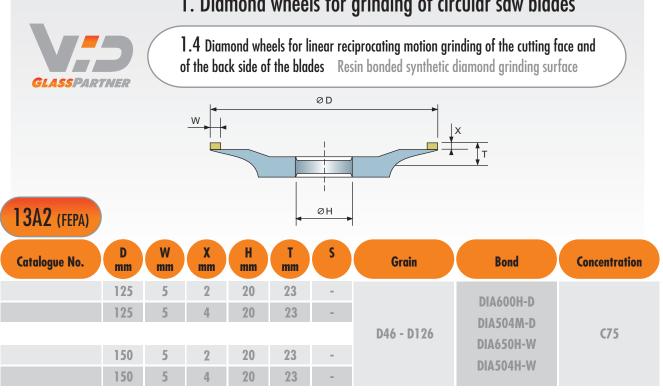
1.4 Diamond wheels for linear reciprocating motion grinding of the cutting face and of the back side of the blades Resin bonded synthetic diamond grinding surface

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4A2 (FEPA)					-	⊘н			
Catalogue No.	D mm	Wmm	X mm	H mm	Tmm	S	Grain	Bond	Concentration
	125	4	2	20	9	15 [°]			
	125	4	3	20	10	15 °			
	125	4	4	20	11	15 [°]			
	125	5	2	20	9	15 °			
	125	5	3	20	10	15 [°]			
	125	5	4	20	11	15			
								DIA600H-D	
	150	4	2	20	11	15°	D46 - D126	DIA504M-D	C75
	150	4	3	20	12	15°		DIA650H-W	
	150	4	4	20	13	15 [°]		DIA504H-W	
	150	5	2	20	11	15			
	150	5	3	20	12	15 [°]			
	150	5	4	20	13	15°			
	200	4	1,5	20	15	15°			
	200	4	3	20	15	15 [°]			

For wet grinding of the sides of the blade, the bond type DIA610H-W(A) using emulsion as coolant or the bond type DIA610H-W(B) using oil as the coolant is recommended, for example at production of the blades with the grinding depth of t=0.15mm for each side.

The use of diamond powder with finer grain reduces the roughness of the processed surface, however, it also shortens the lifetime of the wheel.





For the direct two-way motion grinding of the cutting face of the blade and the ridge of the blade on universal lathes, a narrow width of grinding is characteristic. This allows for enhancing of the grinding regimes (e.g. grinding depth = t), as opposed to grinding of the cutting face of the cutter (see 2.1.). For the given operation the following types of bond are recommended: DIA600H-D(B) and DIA504M-D(B) for dry grinding, and DIA600H-W(A) and DIA504H-W(A) for wet grinding using emulsion as the coolant.

For dry grinding we recommend the bond type DIA600H-D(B) for grinding of narrow surfaces (e.g. b=4mm) and the bond type DIA504M-D(B) for grinding of larger surfaces (e.g. b=8mm).

For wet grinding using emulsion as the coolant with more intensive regimes (e.g. for deep grinding) we recommend the bond type DIA600H-W(A), while DIA504H-W(A) should be used with less intensive regimes.

Bond	Coolant
DIA600H-D(B)	х
DIA504M-D(B)	Х
DIA600H-W(A)	emulsion
DIA504H-W(A)	emulsion

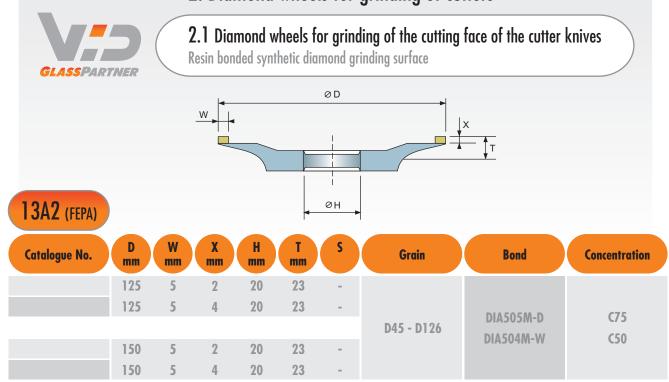


$\mathbf{2.1}$ Diamond wheels for grinding of the cutting face of the cutter knives

Resin bonded synthetic diamond grinding surface

GLASSP AR	RTN/ER								
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		s		 ■				X T	
						ØН			
4A2 (FEPA)					-	•			
atalogue No.	D mm	W	X mm	H	T	S	Grain	Bond	Concentration
	125	4	2	20/32	9	15 [°]			
	125	4	3	20/32	10	15			
	125	4	4	20/32	11	15°			
	125	5	2	20/32	9	15 °			
	125	5	3	20/32	10	15°			
	125	5	4	20/32	11	15 °			
	150	4	2	20/32	11	15 °	D46 - D126	DIA505M-D	C75
	150	4	3	20/32	12	15 °	040-0120	DIA504M-W	C50
	150	4	4	20/32	13	15 [°]			
	150	5	2	20/32	11	15 °			
	150	5	3	20/32	12	15°			
	150	5	4	20/32	13	15°			
	200	4	1,5	20/32	15	15 °			
	200	4	3	20/32	15	15 °			

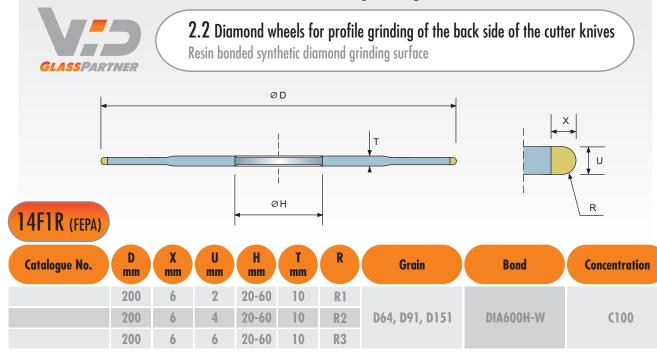
With the bond type **DIA505M-D**, designed for <u>dry</u> grinding, we recommend to use the concentration C75. With the bond type **DIA504M-W**, designed for <u>wet</u> grinding, we recommend to use the concentration C50.



A larger width of grinding (e.g. 25mm and more) is characteristic for grinding of the cutting faces of the cutters on universal lathes. This brings a considerable reduction to the grinding regimes (e.g. grinding depth = t), as opposed to grinding of narrow surfaces (e.g. the ridge of the cutter, see 2.3). For this operation the bond types DIA505H-D(C) for dry grinding and the bond type DIA504M-W(A) for wet grinding using emulsion as the coolant are recommended.

Concentration C100 should be used for <u>dry</u> grinding. Concentration C50 should be used for <u>wet</u> grinding.





For <u>wet</u> profile grinding of the ridge of the cutter the bond type **DIA600H-W(A)** using emulsion as the coolant is recommended, for example at production of the saw blade with the grinding depth of t=0.8mm and the grit D151, or at smooth grinding with the grinding depth of t=0.05mm and the grit D64.





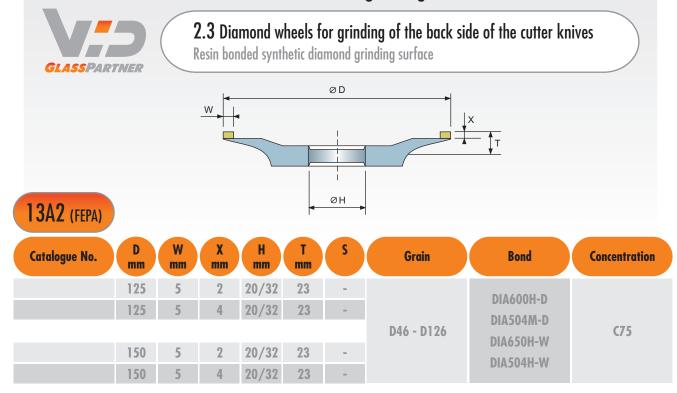


$\mathbf{2.3}$ Diamond wheels for grinding of the back side of the cutter knives

Resin bonded synthetic diamond grinding surface

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		s(— ↓ ⊤	
					1	I I			
4A2 (FEPA)					-	ØН			
Catalogue No.	D mm	W mm	X mm	H mm	T mm	S	Grain	Bond	Concentration
	125	4	2	20/32	9	15 [.]			
	125	4	3	20/32	10	15 [°]			
	125	4	4	20/32	11	15 [°]			
	125	5	2	20/32	9	15°			
	125	5	3	20/32	10	15 °			
	125	5	4	20/32	11	15 [°]			
								DIA600H-D	
	150	4	2	20/32	11	15°	D4/ D10/	D126 DIA504M-D C75 DIA650H-W DIA504H-W	675
	150	4	3	20/32	12	15 [°]	D46 - D126		(75
	150	4	4	20/32	13	15 [°]			
	150	5	2	20/32	11	15 °			
	150	5	3	20/32	12	15 [°]			
	150	5	4	20/32	13	15 [°]			
	200	4	1,5	20/32	15	15 [°]			
	200	4	3	20/32	15	15°			





For grinding of the ridge of the cutter on universal lathes, a narrow width of grinding is characteristic. This allows for enhancing of the grinding regimes (e.g. grinding depth = t), as opposed to grinding of the cutting face of the cutter (see 2.1.).

For the given operation the following types of bond are recommended: DIA600H-D(B) and DIA504M-D(B) for dry grinding, and DIA600H-W(A) and DIA504H-W(A) for wet grinding using emulsion as the coolant.

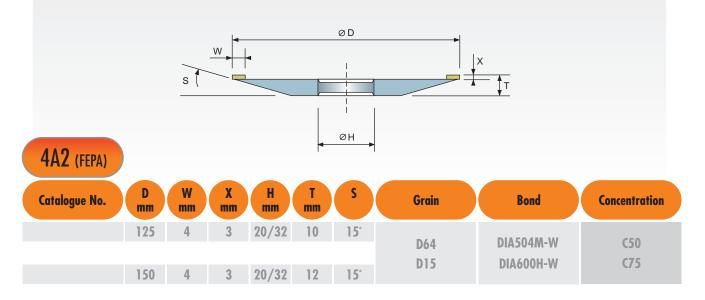
For dry grinding we recommend the bond type DIA600H-D(B) for grinding of narrow surfaces (e.g. b=4mm) and the bond type DIA504M-D(B) for grinding of larger surfaces (e.g. b=8mm). For wet grinding with more intensive regimes (e.g. for deep grinding) we recommend the bond type DIA600H-W(A) using emulsion as the coolant, while DIA504H-W(A) should be used with less intensive regimes.

Bond	Coolant
DIA600H-D(B)	Х
DIA504M-D(B)	X
DIA600H-W(A)	Х
DIA504H-W(A)	Х



3. Diamond wheels for grinding of tungsten carbide knives

Resin bonded synthetic diamond grinding surface



For the preparatory (rough) <u>wet</u> grinding of the cutting face of the tungsten carbide knives, it is recommended to use the bond type **DIA504M-W** and the grain size D64.

For the final (smooth) wet grinding of the cutting face of the tungsten carbide knives, it is recommended to use the bond type **DIA600H-W** and a wheel with the grain size D15 (for example for the grinding depth of t=0.01mm).

The use of the wheels with higher concentration C75, which are more expensive but have a longer lifetime, can be in some cases economically more efficient.

For the given operation it is possible to use also other types of wheels, utilized for grinding of the cutting face of the cutter (2.1) and the cutting face of the saw blade (1.1).

